

# Omega

## Testbeam issues for CALICE/EUDET technological prototypes

8 September, 2008

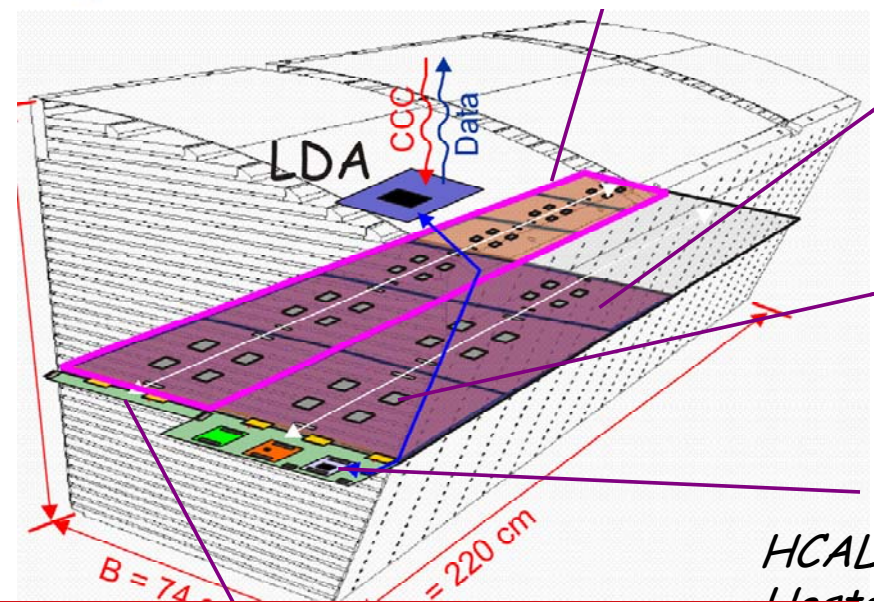
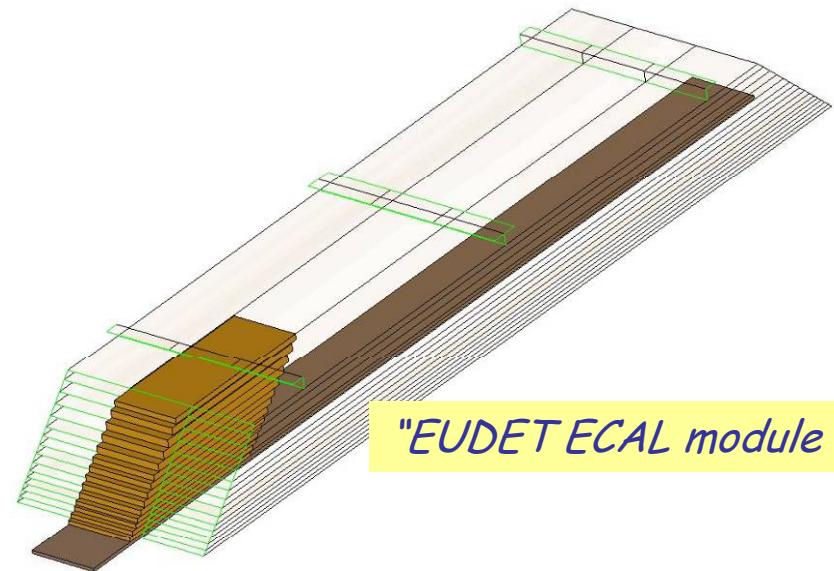
*Orsay MicroElectronic Group Associated*



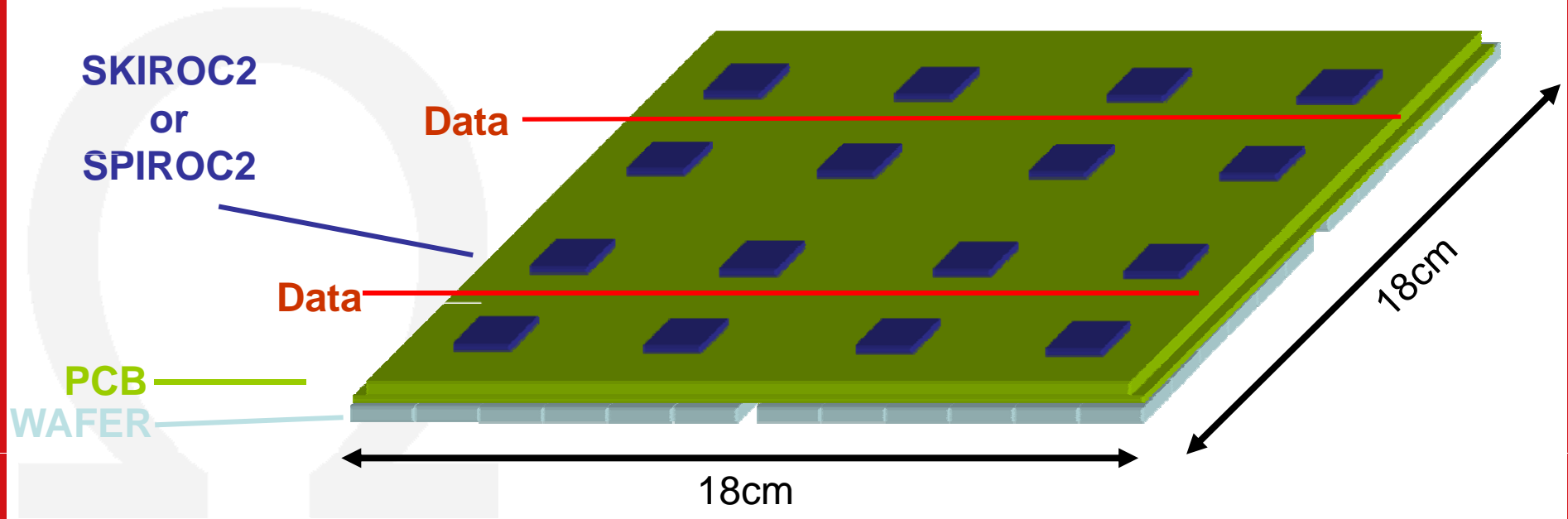
# EUDET module FEE : main issues



- Technical prototype
- Test many technical issues
  - “stictchable” motherboards
  - Minimize connections between boards
  - Reduce PCB thickness to  $<1\text{mm}$
  - Internal supplies decoupling
  - Mixed signal issues
  - Digital activity with sensistive analog front-end
  - Pulsed power issues
  - Electronics stability
  - Thermal effects
  - To be validated in beam



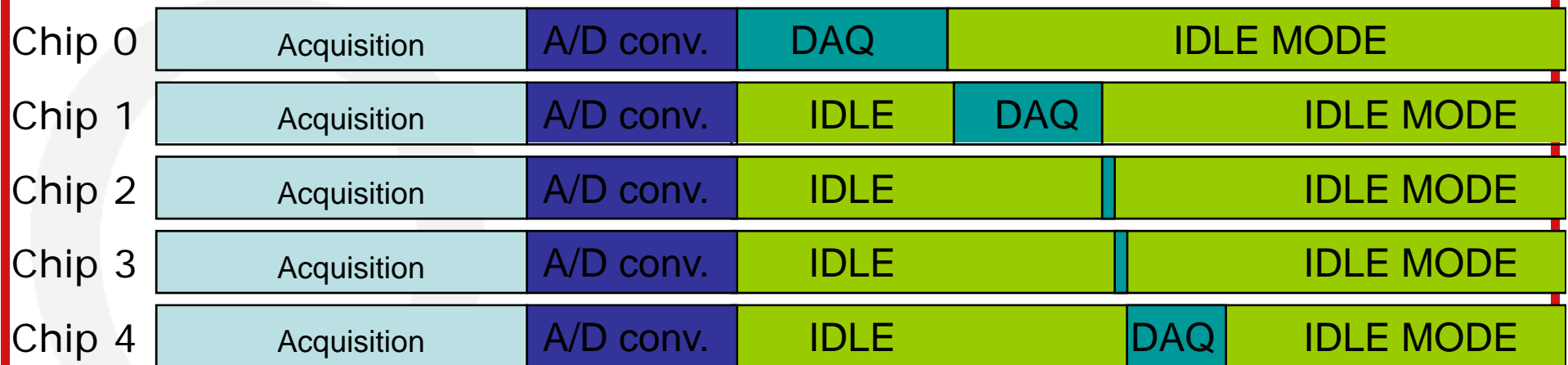
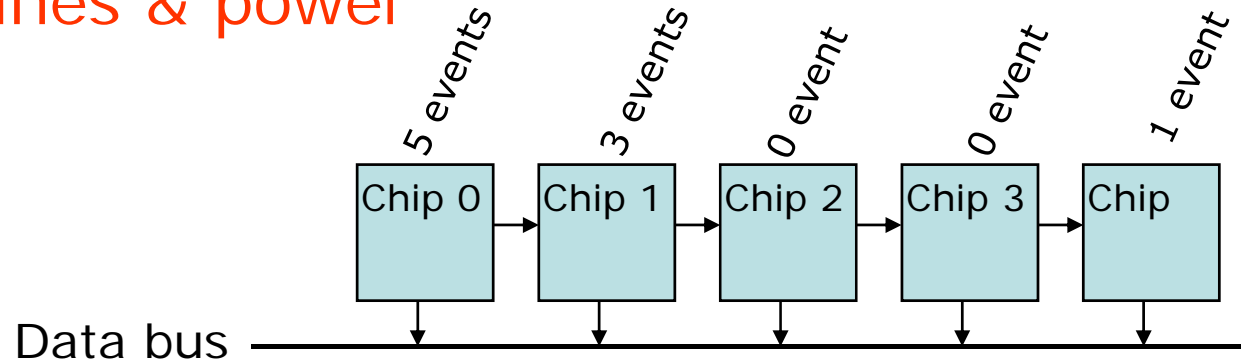
- Front end boards (FEV7)
  - 18cm\*18cm PCB with 6-inch wafers (4 wafers of 9\*9cm)
  - 0.5\*0.5cm<sup>2</sup> pads → 324 pads/wafer → 1296 channels/PCB
  - 16 readout chips (first SPIROC2 then SKIROC2)
  - 2 (duplicated) readout lines => 8 chips/line
  - 16 events\*(32 or 64 channels)\*16bits/chip=8-16kbits/chip



- Readout rate : 1 to 5 MHz
  - 8 chips/ data line \* 16 kbit/chip = 128 kbit/data line
  - Readout time : 25 to 128 ms
  - Acquisition and digitization time negligible (~2 ms)
  - Readout sequences per second : 8 to 40
  - Events per second : 128 to 640
  - 5 MHz with only one board on the slab should be feasible
- « Add » 1% duty cycle
  - Need that digital power pulsing efficient, ie reduced power during readout
  - otherwise 1% ON during 10s beam means OFF during 16mn !!

# Read out : token ring

- Readout architecture common to all calorimeters
- Minimize data lines & power



1ms (.5%)

.5ms (.25%)

.5ms (.25%)

199ms (99%)

1% duty cycle

99% duty cycle

- Figures to be checked and discussed
- Data taking rate: 128 to 640 Hz
- Power pulsing 1%
- Readout time ( $\sim 100\text{ms}$ ) dominates acquisition time
- Cycle similar to ILC (ms)
- Much higher occupancy (16)
- Very pessimistic : assumes all 8 chips full
- What power dissipation during readout ?